

HMA121

HMA124

HMA2701

HMAA2705

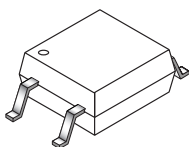
DESCRIPTION

The HMA series consists of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a compact 4-pin mini-flat package. The lead pitch is 2.54 mm.

The HMAA series consists of two gallium arsenide infrared emitting diodes, connected in inverse parallel, driving a single silicon phototransistor in a compact 4-pin mini-flat package.

FEATURES

- Compact 4-pin package (2.4 mm maximum standoff height)
- Current Transfer Ratio in selected groups
HMAA2705: 50-300% HMA121: 50-600%
HMA2701: 50-300% HMA124: 100% MIN
- Available in tape and reel quantities of 500 and 2500.
- Applicable to Infrared Ray reflow (230°C max, 30 seconds.)
- BSI (File #8611/8612), CSA (File #1162301), UL (File #E90700) and VDE (File #136480) certified



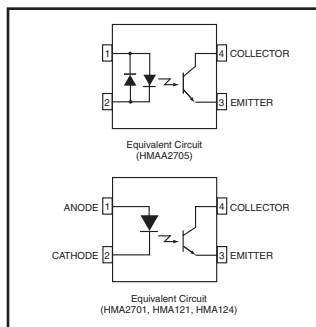
APPLICATIONS

HMAA series

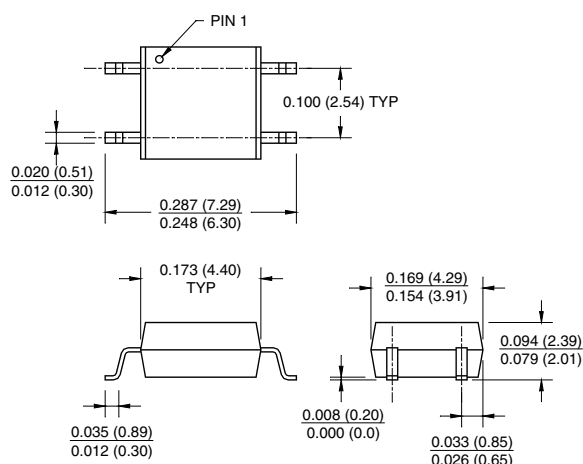
- AC line monitor
- Unknown polarity DC sensor
- Telephone line receiver

HMA series

- Digital logic inputs
- Microprocessor inputs
- Power supply monitor
- Twisted pair line receiver
- Telephone line receiver



PACKAGE DIMENSIONS



NOTE

All dimensions are in inches (millimeters)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Units
TOTAL PACKAGE			
Storage Temperature	T _{STG}	-55 to +150	°C
Operating Temperature	T _{OPR}	-55 to +100	°C
EMITTER			
Continuous Forward Current	I _{F (avg)}	50	mA
Peak Forward Current (1 μs pulse, 300 pps.)	I _{F (pk)}	1	A
Reverse Input Voltage (HMA)	V _R	6	V
Power Dissipation	P _D	70	mW
Derate linearly (above 25°C)		0.65	mW/°C
DETECTOR			
Continuous Collector Current		80	mA
Power Dissipation	P _D	150	mW
Derate linearly (above 25°C)		2.0	mW/°C
Collector-Emitter Voltage	V _{CEO}	40	V
HMA2701, HMAA2705 HMA121, HMA124		80	
Emitter-Collector Voltage	V _{ECO}	7	V

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ELECTRICAL CHARACTERISTICS (T _A = 25°C)								
INDIVIDUAL COMPONENT CHARACTERISTICS								
Parameter	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit	
EMITTER Forward Voltage	(I _F = 10 mA)	V _F	HMA121	1.0		1.3	V	
			HMA124					
	(I _F = 5 mA)		HMA2701			1.4		
	(I _F = ± 5 mA)		HMAA2705					
Reverse Current	(V _R = 5 V)	I _R	HMA2701			5	μA	
			HMA121					
			HMA124					
DETECTOR Breakdown Voltage Collector to Emitter	(I _C = 1 mA, I _F = 0)	BV _{CEO}	HMA121	80			V	
			HMA124					
			HMA2701	40				
			HMAA2705					
Emitter to Collector	(I _E = 100 μA, I _F = 0)	BV _{ECO}	All	7				
Collector Dark Current	(V _{CE} = 40 V, I _F = 0)	I _{CEO}	All			100	nA	
Capacitance	(V _{CE} = 0 V, f = 1 MHz)	C _{CE}	All		10		pF	

TRANSFER CHARACTERISTICS ($T_A = 25^\circ\text{C}$)							
Characteristic	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
DC Current Transfer Ratio	(I _F = ± 5 mA, V _{CE} = 5 V)	CTR	HMAA2705	50		300	%
	(I _F = 5 mA, V _{CE} = 5 V)		HMA2701	50		300	
	(I _F = 5 mA, V _{CE} = 5 V)		HMA121	50		600	
	(I _F = 1 mA, V _{CE} = 0.5 V)		HMA124	100		1200	
	(I _F = 0.5 mA, V _{CE} = 1.5 V)		HMA124	50		—	
CTR Symmetry	(I _F = ± 5 mA, V _{CE} = 5 V)	—	HMAA2705	0.3		3.0	
Saturation Voltage	(I _F = ± 10 mA, I _C = 2 mA)	V _{CE (SAT)}	HMAA2705			0.3	V
	(I _F = 10 mA, I _C = 2 mA)		HMA2701			0.3	
	(I _F = 8 mA, I _C = 2.4 mA)		HMA121			0.4	
	(I _F = 1 mA, I _C = 0.5 mA)		HMA124			0.4	
Rise Time (Non-Saturated)	(I _C = 2 mA, V _{CE} = 5 V) (R _L = 100V)	t _r			3		μs
Fall Time (Non-Saturated)	(I _C = 2 mA, V _{CE} = 5 V) (R _L = 100V)	t _f			3		

ISOLATION CHARACTERISTICS							
Characteristic	Test Conditions	Symbol	Device	Min	Typ**	Max	Unit
Steady State Isolation Voltage	(1 Minute)	V _{ISO}	All	3750			VRMS

** All typicals at T_A = 25°C

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TYPICAL PERFORMANCE CURVES

Fig. 1 Forward Current vs. Forward Voltage

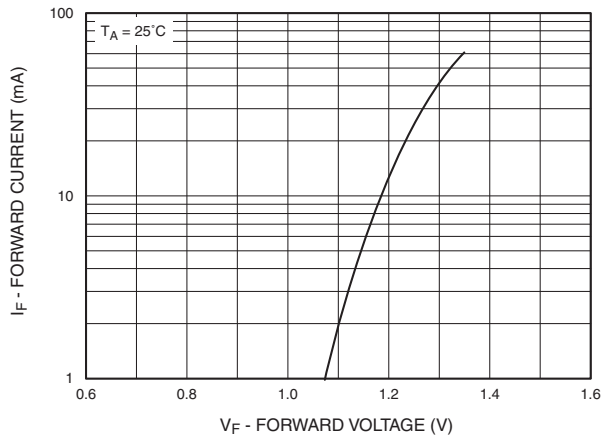


Fig. 2 Collector Current vs. Forward Current

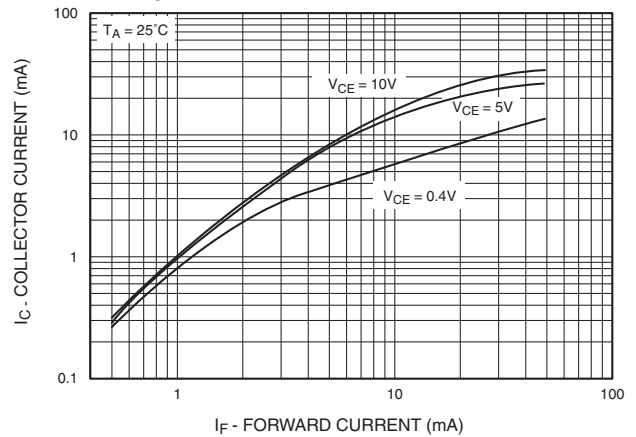


Fig. 3 Current Transfer Ratio vs. Forward Current

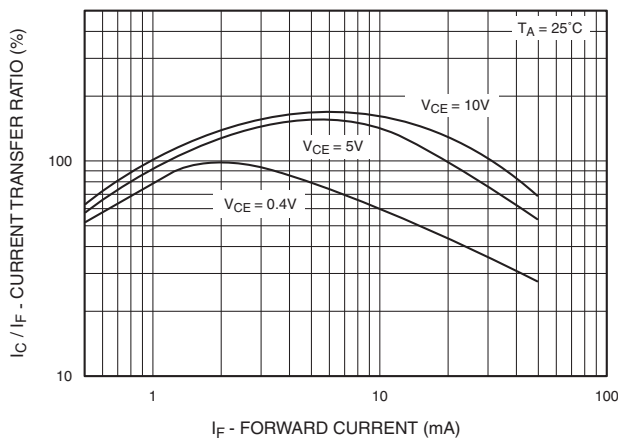


Fig. 4 Collector Current vs. Temperature

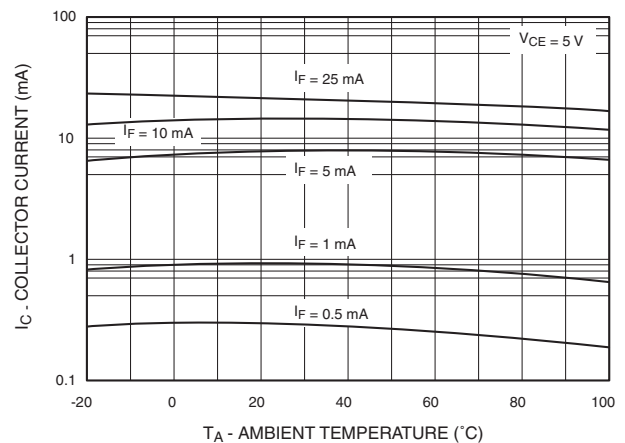
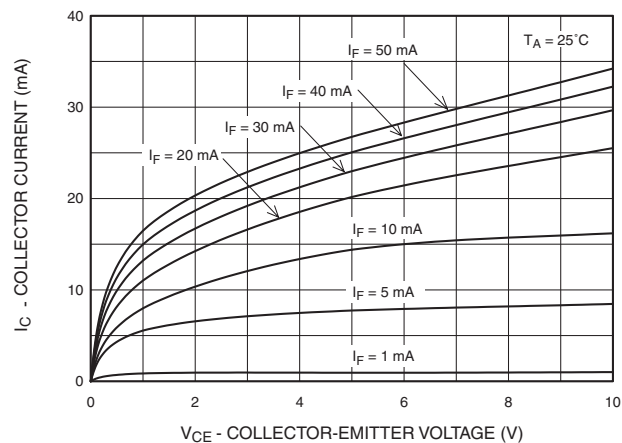


Fig. 5 Collector Current vs. Collector-Emitter Voltage



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Fig. 6 Collector Current vs. Collector-Emitter Voltage

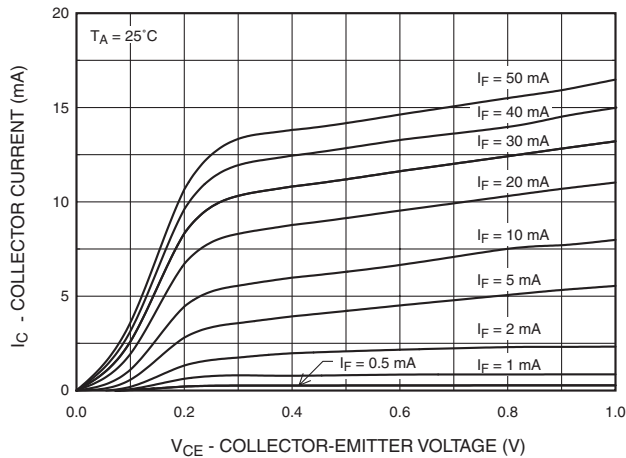


Fig. 7 Collector Dark Current vs. Temperature

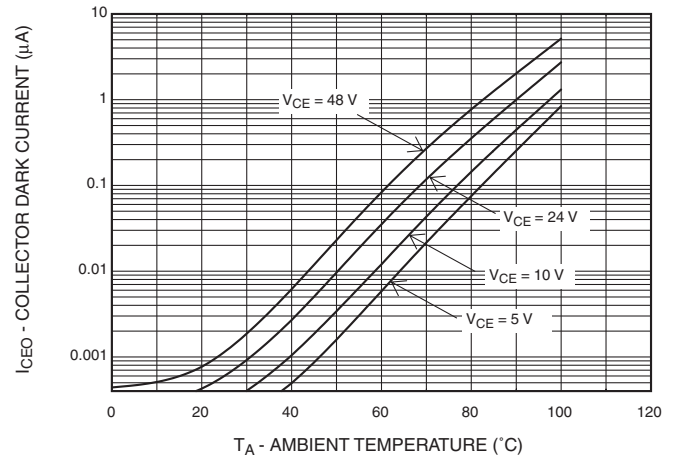


Fig. 8 Switching Time vs. Load Resistance

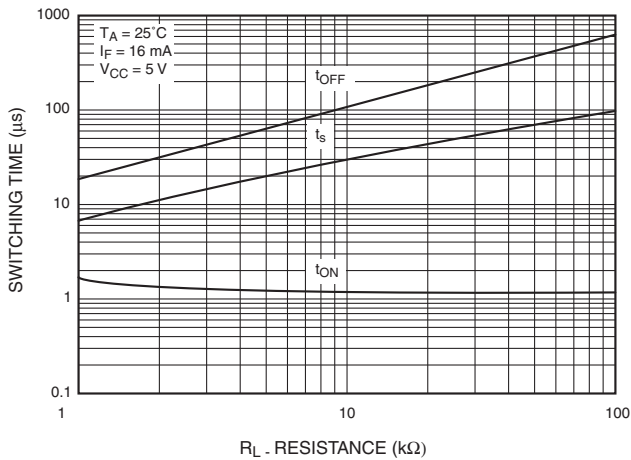
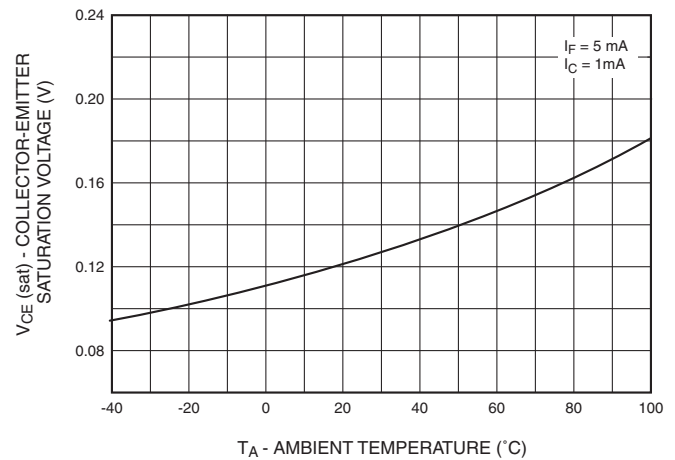


Fig. 9 Collector-Emitter Saturation Voltage vs. Temperature



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ORDERING INFORMATION

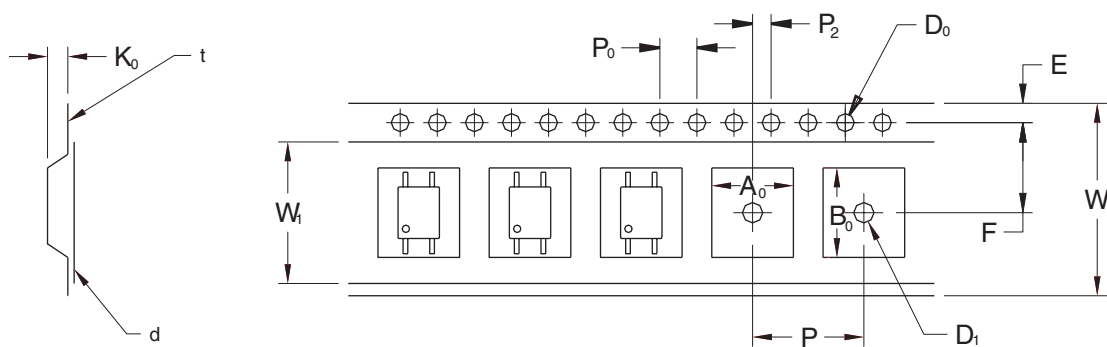
Option	Description
V	VDE Approved
R1	Tape and Reel (500 units)
R2	Tape and Reel (2500 units)
R1V	Tape and Reel (500 units) and VDE Approved
R2V	Tape and Reel (2500 units) and VDE Approved

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		2.54 Pitch
Description	Symbol	Dimensions (mm)
Tape Width	W	12.00±0.4
Tape Thickness	t	0.30±0.20
Sprocket Hole Pitch	P ₀	4.00±0.20
Sprocket Hole Dia.	D ₀	1.55±0.20
Sprocket Hole Location	E	1.75±0.20
Pocket Location	F	5.50±0.20
	P ₂	2.00±0.20
Pocket Pitch	P	8.00±0.20
Pocket Dimension	A ₀	4.40±0.20
	B ₀	7.30±0.20
	K ₀	2.30±0.20
Pocket Hole Dia.	D ₁	1.55±0.20
Cover Tape Width	W _i	9.20
Cover Tape Thickness	d	0.065±0.02
Max. Component Rotation or Tilt		20° max
Devices Per Reel	R1	500
	R2	2500
Reel Diameter	R1	178 mm (7")
	R2	330 mm (13")

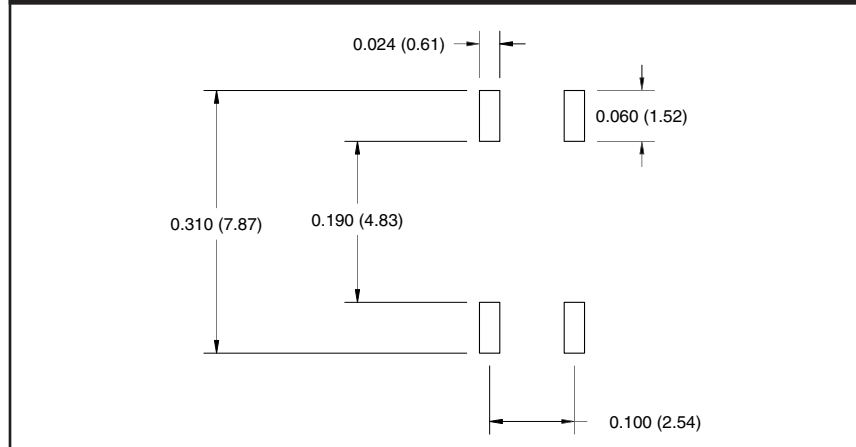
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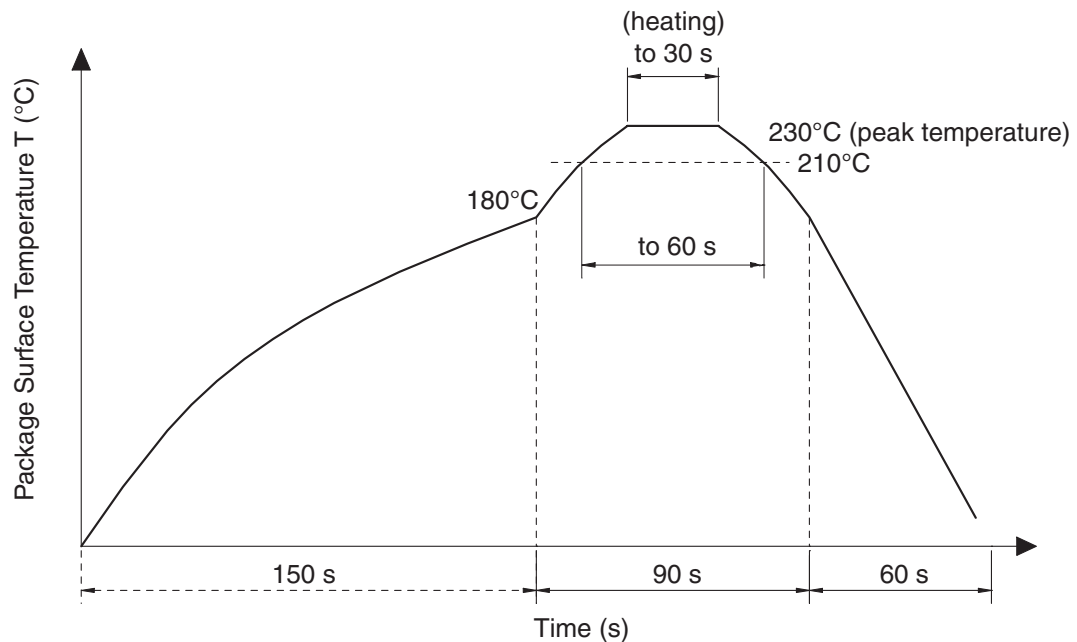
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Footprint Drawing for PCB Layout



Recommended Infrared Reflow Soldering Profile



- Peak reflow temperature: 230°C (package surface temperature) for 30 seconds
- Time of temperature higher than 210°C: 60 seconds or less
- One time soldering reflow is recommended

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